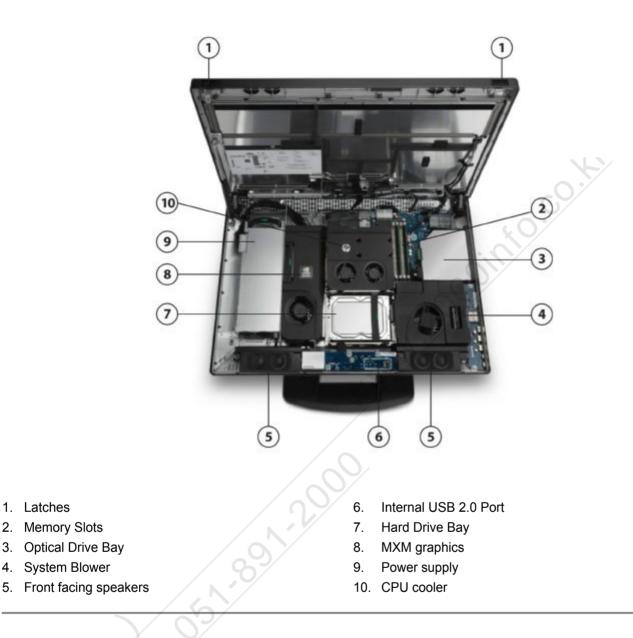
Overview





1. Latches

2.

5.



- 1. Power Button
- 2. System Activity LED
- 3. Optical Drive Eject Button
- 4. Slot load Optical Drive

- 5. 4-in-1 Media Card Reader
- 6. Firewire 1394a
- 7. USB 3.0 (2 ports)
- 8. Audio In/Out





- 1. Digital Microphone array
- 2. HD Webcam
- 3. Front Facing Speakers
- 4. Stand
- 5. 27" LED backlit IPS Display

Overview



- 1. Audio In/Out, Subwoofer Out
- 2. 4 USB 2.0 ports
- 3. S/PDIF (digital optical audio)

LAN
 DisplayPort In/Out
 Power

Form Factor	All in One
Operating Systems	Windows 8 Pro 64-bit Windows 8 Simplified Chinese Edition 64-bit Windows 8 Pro Downgrade to Windows 7 Professional 32-bit Windows 8 Pro Downgrade to Windows 7 Professional 64-bit Genuine Windows®7 Professional 32-Bit(1) Genuine Windows®7 Professional 64-Bit(1) HP Linux Installer Kit(2) SUSE Linux Enterprise Desktop 11 (90 day license) (4)
	 Red Hat Enterprise Linux Desktop/Workstation (3,4) NOTE 1: Systems may require upgraded and/or separately purchased hardware and/or DVD drive to install the Windows 7 software and take full advantage of Windows 7 functionality. See http://www.microsoft.com/windows/windows-7/ for details. NOTE 2: HP Linux Installer Kit Includes drivers for 32-bit and 64-bit OS versions of Red Hat Enterprise Linux (RHEL) 5 Workstation, RHEL 6 Workstation, and 64-bit SUSE Linux Enterprise Desktop (SLED) 11. See http://www.hp.com/go/linux for details. NOTE 3: RHEL Desktop is not available as a preinstall from HP. RHEL Desktop is only available as a one-year paper license drop-in-the-box. NOTE 4: For detailed OS/hardware support information for Linux, see: http://www.hp.com/support/linux hardware matrix.



Available Processors	Name	Cores	Speed	Intel®Turbo Boost Technology		Memory Speed (MT/s)	Hyper- Threading	Intel®	Intel® HD Graphics	TDP (W)
	Intel®Xeon® processor E3-1280v2	4	3.6	4.0	8	1600	Y	Y	N/A	69W
	Intel®Xeon® processor E3-1245v2	4	3.4	3.8	8	1600	Y	Y G	Intel HD Graphics P4000	77W
	Intel®Xeon® processor E3-1225v2	4	3.2	3.6	8	1600	N	Y	Intel HD Graphics P4000	77W
	Intel®Core™ i5-3470 processor	4	3.2	3.6	6	1600	N	Y	Intel HD Graphics 2500	77W
	Intel®Core™ i3-3220 processor	2	3.3	N/A	3	1600	N	N	Intel HD Graphics 2500	55W
	¹ The specification processor core within 100MHz increased	when a	ccelera	ted with Intel	Turbo E	loost Tec	hnology. Ti	urbo boost ste	epping oc	curs
Available Processor Disclaimers	Intel Xeon E3 ar Intel's numbering features within e http://www.intel. 64-bit computing BIOS, operating Processor will no BIOS. Performan http://www.intel. Dual-Core and C software produc operating syster all customers or	g is not each pro- com/pr g on Int systen ot opera- nce will Quad-C ts and I n softw	a measo occesso oducts/ el®64 a n, devic ate (inc vary du fo/em6- ore tecl hardwa are for	surement of h r family, not a processor_nu architecture re- ce drivers and luding 32-bit of epending on y 4t for more info nnologies are re-aware mult full benefits; of	gher pe cross d mber/ f equires applica operatio our har ormatio designe itasking heck w	erformand ifferent p for details a compu- tions ena n) withou dware an n. ed to impr g operatir ith softwa	ce. Process rocessor fa s. bled for Int it an Intel 6 d software rove perform g systems are provide	or numbers of milies. See: with a process el 64 architecture configuration nance of mult and may requir to determine	lifferentiate sor, chips cture. e-enabled s. See: ithreaded uire appro e suitability	et, priate
Integrated Display	See below for de Panel Type: IPS (in-pla Viewable Image Screen Opening Optimal Resolut	ane swi Area: () (W x H ion: 25	itching) 68.5 cn H): 59.8 60 x 14	LED Backlit L n, (27 in.) wide 3 x 33.6 cm, (2 440 @ 60 Hz;	escreen 23.5 x 1	•	illy measur	ed		
	Aspect Ratio: 16:9 Widescreen Viewing Angle (typical): Up to 178° horizontal/178° vertical (10:1 minimum contrast ratio)									
	Maximum Brightness (typical)*: 380 nits cd/m2									
	Minimum Brightness (typical)*: 50 nits cd/m2									
	Contrast Ratio (Dynamic Contra									
	DA - 14263	Wo	rldwide	QuickSpecs -	-Versio	on 22 —4-	1-2015		Pag	ge 5

Non-operating	8% to 90%					
	8% to 85%					
Non-operating	-40° to 140°F (-40° to 60°C)					
	40° to 95°F (5° to 35°C)					
Exact weights depend upon co Max system weight WITH star Stand weight 5.9 kg (13 lbs)	onfiguration;					
3.2in.)	VITHOUT stand: 457.2mm x 660.4mm x 81.28mm (18in. x 26in. x					
	VITH stand: 584.2mm x 660.4mm x 419.1mm (23in. x 26in. x 16.5in.);					
	, 1 RJ45 LAN, 1 Subwoofer Output, 1 optical S/PDIF Output, 1 Audio					
	board, 2 internal on 9-pin header					
to function as Line-in	-in-1 Media Card Reader, 1 Headphone, 1 Mic; Mic can be re-tasked					
• 2 internal 2.5" bays						
• 1 internal 3.5" bay, or						
 1 MXM (dedicated for grain of the second s	aphics)					
The Z1 can either be placed o with the industry standard VES pattern.	n the desktop in the traditional display method or mounted on a wall SA mount. The VESA mount on the Z1 uses a 100x100 VESA mount					
	(non-interlaced): 2560 x 1440 @ 60 Hz					
	0 @ 60 Hz: 3.7MP					
Horizontal Frequency: 90 kHz						
Notes : ** Display of up to 1.07 Signal Interface/Performance	' billion colors on HP Z1 requires use of 10-bit content.					
1 · · · · · · · · · · · · · · · · · · ·	fications represent the typical specifications provided by HP's tual performance may vary either higher or lower.					
Color Support**: Up to 1.07 bil	lion colors					
Color Gamut Coverage of sRG	iB: 100% (CIE 1931)					
Color Gamut Area vs. NTSC: 9	96% (CIE 1976), 77% (CIE 1931)					
Backlight Lamp Life (to half bri	Backlight Lamp Life (to half brightness): 39,000 hours minimum					
Pixel Pitch: 0.2331 mm						
	ms (gray to gray); 14 ms (on/off)					
	Pixel Pitch: 0.2331 mm Backlight Lamp Life (to half br Color Gamut Area vs. NTSC: 9 Color Gamut Coverage of sRG Color Support**: Up to 1.07 bil Notes: *All performance speci component manufacturers; act Notes: ** Display of up to 1.07 Signal Interface/Performance Horizontal Frequency: 90 kHz Vertical Frequency: 60 Hz Native Resolution: 2560 x 144 Preset VESA Graphic Modes i Maximum Pixel Clock Speed: User Programmable Modes: N Default Color Temperature: 65 The Z1 can either be placed o with the industry standard VES pattern.					



(non-pressurized) Power Supply	Operating: 3,000 m (10,000 ft)
Power Supply	Non-operating 9,100 m (30,000 ft).
Sower Suppry	400 watts wide-ranging, active Power Factor Correction, 90% Efficient
	The Device Cumply Efficiency Depart for this and dust may be found at these lister TDD
Chinact	The Power Supply Efficiency Report for this product may be found at these links: TBD
Chipset Memory	Intel®C206 chipset
Memory Memory Disclaimers	4 DIMM slots, supporting up to 32GB ECC or 16GB non-ECC Unbuffered DDR3 1600 MT/s The CPU determines the speed at which the memory is clocked. If a 1333MT/s capable CPU is
mentory Discialitiers	used in the system, the maximum speed the memory will run at is 1333MT/s regardless of the
	specified speed of the memory.
Norkstation ISV	See the latest list of certifications at
Certifications	http://www.hp.com/united-states/campaigns/workstations/partnerships.html
	21.051.891.2000

Supported Components

Processors		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	2nd generation Intel®Core™processor family				
	Intel®Xeon®processor E3 v2 family (Z220/Z1)				
	Intel®Xeon®processor E3-1280v2, Quad-Core, 8 MB cache, 3.6 GHz, up to 4.0 GHz with Intel Turbo Boost Technology	Y	Y		See Note 1
	Intel®Xeon®processor E3-1245v2, Quad-Core, 8 MB cache, 3.4 GHz, up to 3.8 GHz with Intel Turbo Boost Technology	Y	Y		See Note 1, 2
	Intel®Xeon®processor E3-1225v2, Quad-Core, 8 MB cache, 3.2 GHz, up to 3.6 GHz with Intel Turbo Boost Technology	Y	Ŷ		See Note 1, 2
	3rd generation Intel®Core™processor family				
	Intel®Core™5-3470 processor, Quad-Core, 6 MB cache, 3.2 GHz, up to 3.6 GHz with Intel Turbo Boost Technology	Ý	Y		
	Intel®Core™3-3220 processor, Dual-Core, 3 MB cache, 3.3 GHz	Y	Y		See Note 1
	NOTE 1 : These processors support either ECC or non NOTE 2 : Intel HD Graphics P4000 provides improved of workstation-specific graphics drivers for improved com professional applications compared to Intel HD Graphi	lesktop perfor patibility and p	mance ar		

Monitors / Displays

/Ionitors / Displays		Factory Configured	Option Kit	Option Kit Part Number	
	HP Z1 27-inch WLED IPS Display				
	HP DreamColor LP2480zx Professional Display				
	HP ZR30w 30-inch S-IPS LCD Monitor				
	HP ZR2740w 27-inch LED Backlit IPS Monitor				
	HP ZR2440w 24-inch LED Backlit IPS Monitor				
	HP Z Display Z24i 24-inch IPS LED Backlit Monitor				
	HP Z Display Z23i 23-inch IPS LED Backlit Monitor				
	HP Z Display Z22i 21.5-inch IPS LED Backlit Monitor				
	NOTES:				
× k	Supported by all Operating Systems available from HP				
	Screen Size Diagonally Measured				



Supported Components

HP Z1 Workstation

Hard Drives

SATA Hard Drives			actory nfigured	Option Kit	Optio Kit Pa Numb	rt Suppor		
	SATA (Serial ATA) Hard Drives for HP		U					
	250GB SATA 7200 rpm 6Gb/s 3.5" HDD)	Y	Y				
	500GB SATA 7200 rpm 6Gb/s 3.5" HDD)	Y	Y				
	1TB SATA 7200 rpm 6Gb/s 3.5" HDD		Y	Y				
	300GB SATA 10K rpm SFF HDD		Y	Y				
	600GB SATA 10K rpm SFF HDD		Y	Y	67			
	500GB SATA 10K rpm SFF HDD		Y	Y)	B8X19/	٩A		
	1TB SATA 10K rpm SFF HDD		Y	Y	B8X20/	٩A		
	3.0TB SATA 7200 rpm 6Gb/s 3.5" HDD		YXC	Y	QF298	AA		
SATA Solid State	HP Solid State Drives (SSDs) for Worl	kstations	\sim					
Drives	HP 256GB SATA 6Gb/s SSD		Y	Y	A3D26	AA		
	HP 512GB SATA 6Gb/s SSD		Y	Y	D8F30	٩A		
Hard Drive				Opti	on Kit			
Controllers		Factory Configured	Option Kit		art mber	Support Notes		
	Factory integrated RAID on motherboard for SATA drives							
	RAID 0 Configuration - Striped Array	Y	Ν					
	RAID 1 Configuration - Mirrored Array	Y	Ν					
	SATA hardware RAID is not supported on L RAID, provides excellent functionality and per RAID. Please visit http://h20000.www2.hp.com/bc/docs/support capabilities with Linux.	erformance. It is a	good alte	rnative to	hardwa	re-based		
	All drives must be identical in type and capa	acity						
	All RAID arrays must be less than 2 TB							

NOTE 1: Requires identical hard drives (speeds, capacity, interface).



Supported Components

Graphics

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes	Supported Multi Mixed
Integrated Intel HD Graphics Media	Accelerators				
Intel HD Graphics P3000	Y	Ν		On select CPUs	1
Intel HD Graphics 2000	Y	Ν		On select CPUs	1
Integrated Intel HD Graphics Media	Accelerators	(Z220)			
Intel HD Graphics P4000	Y	Y	4	On select CPUs	1
Intel HD Graphics 2500	Y	Y	~0	On select CPUs	1
Entry 3D			9		
NVIDIA Quadro 500M 1GB Graphics	Y	Ν			1
Mid-range 3D		•.•	\bigvee		
NVIDA Quadro 1000M 2GB Graphics	Y	Ν			1
NVIDIA Quadro K3000M 2GB Graphics	s Y	Y		C3G85AA	1
High End 3D					
NVIDIA Quadro K4000M 4GB Graphics	s Y	Y		C3G86AA	1
NOTE 1: If a discrete graphics card is i	nstalled, Intel	integrate	d graphics is	s disabled.	

Memory

СТО

Option Kit Part Support Notes Number

DDR3-1600 ECC Unbuffered DIMMs - CTO HP 32GB (4x8GB) DDR3-1600 ECC RAM HP 16GB (2x8GB) DDR3-1600 ECC RAM HP 16GB (4x4GB) DDR3-1600 ECC RAM HP 8GB (2x4GB) DDR3-1600 ECC RAM HP 8GB (4x2GB) DDR3-1600 ECC RAM HP 4GB (2x2GB) DDR3-1600 ECC RAM DDR3-1600 nECC Unbuffered DIMMs CTO HP 16GB (4x4GB) DDR3-1600 nECC RAM HP 8GB (2x4GB) DDR3-1600 nECC RAM HP 8GB (4x2GB) DDR3-1600 nECC RAM HP 4GB (1x4GB) DDR3-1600 nECC RAM HP 4GB (1x4GB) DDR3-1600 nECC RAM HP 4GB (1x4GB) DDR3-1600 nECC RAM HP 4GB (1x2GB) DDR3-1600 nECC RAM HP 4GB (1x2GB) DDR3-1600 nECC RAM

Intel®Xeon E3 and Intel Core i3 processors can support either ECC or non-ECC memory.

Two channels of DDR3 memory are supported. To realize full performance at least one DIMM must be inserted into each channel.

The CPU determines the speed at which the memory is clocked. If a 1333MT/s capable CPU is used in the system, the maximum speed the memory will run at is 1333MT/s regardless of the specified speed of the memory.

Only unbuffered DDR3 DIMMs are supported.

Supported Components

	AMO				
	DDR3-1600 ECC Unbuffered DIMMs - AMO				
	HP 8GB (1x8GB) DDR3-1600 ECC RAM		A2Z50AA	١	
	HP 4GB (1x4GB) DDR3-1600 ECC RAM		A2Z48AA	١	
	HP 2GB (1x2GB) DDR3-1600 ECC RAM		A2Z47AA	۱.	
	DDR3-1600 nECC Unbuffered DIMMs AMO				
	HP 2GB (1x2GB) DDR3-1600 nECC RAM		B1S52AA	4	
	HP 4GB (1x4GB) DDR3-1600 nECC RAM		B1S53AA	A	
Multimedia and Audic)			Opt	ion
Devices		Fact Config		otion Kit F Kit Num	Part Suppor Iber Notes
	HP HD 2MP 1080p Webcam	Y		N	
	Integrated HP Digital Mic Array	Y		Ν	
Optical and Removable Storage		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Slot Load DVD+/-RW Drive	Y	N		
	HP Blu-ray Writer Slot Load	Y	Y	B2P97AA	
	other lawful uses. Double Layer discs can store n double-layer discs burned with this drive may not DVD drives and players. As Blu-ray is a new format containing new techno compatibility and/or performance issues may aris Flawless playback on all systems is not guarante may require a DVI or HDMI digital connection and DVD movies cannot be played on this workstation	be compatib ologies, certa se, and do no eed. In order d your display	ain disc, d ain constitution for some	igital connected te defects ir Blu-ray title	single-layer ction, the product s to play, the
Networking and	6		•	Option	-
Communications		Factory Configured	Option d Kit	Kit Part Number	Support Notes
	Integrated Intel 82579LM PCIe GbE Controller	Y	N	Number	NOLES
	Integrated Intel Centrino Advanced-N 6230, Dual	Y	N		See note 1
-	Band with dual antenna TX/RX streams at 300Mbs 802.11 a/g/n Wireless LAN & Bluetooth®Combo Card	I	N		
	NOTE 1: Card is factory installed into miniPCIe s	lot 1.			
Racking and Physical Security		Fact Config		Opti otion Kit F Kit Num	Part Suppor
	LID Changin Interview Conserv			~	

HP Chassis Intrusion Sensor HP Keyed Cable Lock Kit

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BV411AA

HP Z1 Workstation

Supported Compon	ients				
Input Devices		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP USB Standard Keyboard	Y	Y		
	HP USB 2-Button Optical Scroll Mouse	Y	Y		
	HP Wireless Keyboard and Mouse	Y	Y		

Other Hardware		Factory Configured	•	Option Kit Part Number	Support Notes
	HP Power Cord Kit	Ν	Y		
	HP Workstation Mouse Pad	Y	N		Japan only
	HP ENERGY STAR Qualified Configuration	Y, O	N		

Coffman		i.			
Software		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Performance Advisor	Ý	Ν		See note 1
	HP Remote Graphics Software (RGS) 6.0	Y	Ν		See note 2
	HP ProtectTools Security	Y	Ν		See note 3
	HP Power Assistant	Y	Ν		
	PDF Complete - Corporate Edition	Y	Ν		
	Cyberlink Media Suite & PowerDVD	Y	Ν		Media playback/authoring software
	MS Office Home & Business 2013	Y	Ν		See note 4
	NOTE 1: Available as a free download here: www	w hn com/do/r	erformar	nceadvisor	

NOTE 1: Available as a free download here: www.hp.com/go/performanceadvisor **NOTE 2**: Supports both 32 and 64 bit versions of Windows 7 Professional and Enterprise, Windows XP Professional and Enterprise, and RHEL V6 **NOTE 3**: Must select as a Configure to Order option. Delivered as a "Drop in the Box" CD **NOTE 4**: Available CTO as a "Drop in the Box" addition.

Operating Systems	Support Notes
Genuine Windows®7 Professional 64-bit	See note 1
Genuine Windows®7 Professional 32-bit	See note 1
HP Linux Installer Kit	See note 2
SUSE Linux Enterprise Desktop 11	See note 2
Red Hat Enterprise Linux (RHEL) Workstation - Paper License (1yr)	See note 3
Windows 8 Pro 64-bit	
Windows 8 Simplified Chinese Edition 64-bit	
Windows 8 Pro Downgrade to Windows 7 Professional 32-bit	
Windows 8 Pro Downgrade to Windows 7 Professional 64-bit	
NOTE 1 : See http://www.microsoft.com/windows/windows-7/ for suppo NOTE 2 : For detailed OS/hardware support information for Linux, see: http://www.hp.com/support/linux_hardware_matrix.	rt details.
NOTE 3 : This second OS must be ordered with the HP Linux Installer I	Kit as the first OS.



System Board					
System Board Form Factor	Custom Motherboard, Custom Rear IO board, Custom Side IO board				
Processor Socket	Single LGA 1155				
CPU Bus Speed	DMI				
Chipset	Intel®PCH C206				
Super I/O Controller	Nuvoton NPCD379H				
Memory Expansion Slots	4 DDR3 memory slots				
Memory Type Supported	2GB, 4GB, and 8GB ECC Unbuffered DIMMs; 2GB non-ECC Unbuffered DIMMs				
Memory Speed Supported	Mixing of ECC and non-ECC DIMMs i Up to 1600MT/s DDR3	s not supported.			
Maximum Memory	32GB ECC or 8GB non-ECC				
PCI Express Connectors	1 MXM slot (PCIe Gen2 x16, DP x 2) 3 miniPCIe slots (PCIe Gen2 x1, USB	2.0)			
Supported Drive Interfaces	SATA	Integrated Serial ATA interfaces (2x 6Gb/s SATA, 1x 3Gb/s SATA). NOTE: the Z1 supports a maximum of two SATA SFF/SSD drives only. RAID 0 and 1 supported. (Factory integrated RAID is Microsoft Windows only).			
	Integrated RAID	NOTE: Requires identical hard drives (speeds, capacity, interface)			
	Integrated Graphics	 Integrated Intel HD Graphics 2000 (on Intel Core i3 processors). Integrated Intel HD Graphics P3000 (on Intel Xeon E3-12x5 processors). Unified Memory Architecture (UMA)- A region of system memory is reserved and dedicated to the graphics display. DirectX 10.0 compliant. OpenGL 3.0 on Intel HD Graphics P3000) Integrated graphics can support dual display across the embedded DP to the LCD panel and the DP output on the Rear IO. 			
	Network Controller	Integrated Gbit LAN MAC by Intel PHY Lewisville 82579LM; Management capabilities WOL, PXE 2.1 and AMT 7			
IEEE 1394 Connector(s)	Side	1 IEEE 1394a			
USB Connector(s)	Side	2 USB 3.0			
	Rear	4 USB 2.0			
	Internal	1 USB 2.0 Type A, 2 USB 2.0 on a 9-pin header			
HD Integrated Audio	Intel HD / IDT 92HD91 codec				
Flash ROM	Yes				
CPU Fan Header	Yes				
Front Control Panel/Speaker Heade	Yes r				



System Technical Specifications

CMOS Battery Holder - Lithium	Yes
Integrated Trusted Platform Module	Integrated TPM 1.2. TPM module disabled where restricted by law.
Power Supply Headers	Yes
Power Switch, Power LED & Hard Drive LED Header	Yes
Clear Password Jumper	Yes
Keyboard/Mouse	USB or Wireless

Power Supply

Power Supply	400W 90% Efficient, Custom PSU (Wide Ranging, Active PFC)			
Operating Voltage Range	90-264	VAC		
Rated Voltage Range	100-240 VAC	118 VAC		
Rated Line Frequency	50-60 Hz	400 Hz		
Operating Line Frequency Range	47-63 Hz	393-407 Hz		
Rated Input Current	5A @ 100-240 VAC	4.5A @ 118 VAC		
Heat Dissipation (Configuration and software dependent)	Typical: 682 btu/h Maximum: 1365 btu			
Power Supply Fan	(2) 40x20 mm v	variable speed		
ENERGY STAR Qualified (Configuration dependent)	Ye	S		
80 PLUS®Compliant	Yes, 90% The Z1 400W power supply efficier http://www.plugloadsolutions.com/psu_re 001_ECOS%202720.1	ncy report can be found at this link: eports/HEWLETT%20PACKARD_650503-		
FEMP Standby Power Compliant @115V	Ye	S		
ErP LOT6 Compliant @ 230V (<0.5 W in S5 - Power Off)	Ye	S		
CECP Compliant @ 220V (<4W in S3 - Suspend to RAM)	Yes; Configurat	tion dependent		
Power Consumption in sleep mode (as defined by ENERGY STAR) - Suspend to RAM (S3) (Instantly Available PC)	<4	W		
Built-in Self Test LED	Ye	s		
Surge Tolerant Full Ranging Power Supply (withstands power surges up to 2000V)	Ye	S		

System Configuration

	i						1
Example Configuration	Processor Info	1xIntel Core i3-2120					
#1	Memory Info	2x2GB DDR3 1600 nECC (UDIMM)					
	Graphics Info	1xNVIDIA (2500M				
	Disks/Optical/Floppy	1x250GB S	ATA/1x16X	DVD-ROM	SATA		
	Power Supply	400W 90%	Custom PS	U			
	Other						
Energy Consumption		115	VAC	230	VAC	100	VAC
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	119	9 W	118	3 W	120	W
	Windows Busy Typ (S0)	165 W 163 W		166 W			
	Windows Busy Max (S0)) 171 W		168 W		172 W	
	Sleep (S3)	2.54 W	2.43 W	2.73 W	2.62 W	2.52 W	2.42 W
	Off (S5)	1.04 W	0.93 W	1.21 W	1.10 W	1.02 W	0.92 W
	Zero Power Mode (EuP)				9		
Heat Dissipation**		115	VAC	230	VAC	100	VAC
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	40	06	40	02	4(09
	Windows Busy Typ (S0))) 563		5	56	56	66
	Windows Busy Max (S0)	583		57	73	58	37
	Sleep (S3)	8.67	8.29	9.32	8.94	8.60	8.26
	Off (S5)	3.55	3.17	4.13	3.75	3.48	3.14
	Zero Power Mode (EuP)		S.				

<i>Example Configuration</i> #2	Memory Info Graphics Info Disks/Optical/Floppy	1xIntel Xeon E3-1280 4x4GB DDR3 1600 ECC (UDIMM) 1xNVIDIA Q3000M 1x500GB SATA/1x16X DVD+-RW SuperMulti SATA 400W 90% Custom PSU					
Energy Consumption		115 VAC 230 VAC 100 VAC					
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	130	130 W 12		5 W	129	9 W
	Windows Busy Typ (S0)	253 W 253 W		3 W	256 W		
	Windows Busy Max (S0))) 287 W		291 W		283 W	
	Sleep (S3)	2.89 W	2.78 W	3.08 W	2.97 W	2.87 W	2.77 W
	Off (S5)	0.99 W	0.88 W	1.16 W	1.06	0.98 W	0.87 W
	Zero Power Mode (EuP)	uP)					
Heat Dissipation**		115	VAC	230	VAC	100	VAC
(Btu/hr)	· •/	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
7,0	Windows Idle (S0)	444		427		440	
	Windows Busy Typ (S0)	86	63	863		874	
	Windows Busy Max (S0)	97	79	993		966	
	Sleep (S3)	9.86	9.49	10.51	10.13	9.79	9.45
	Off (S5)	3.38	3.00	3.96	3.62	3.34	2.97
	Zero Power Mode (EuP)						



Example Configuration	Processor Info	1xIntel Xeon E5-1280					
#3	Memory Info	4x8GB DDR3 1600 (UDIMM)					
	Graphics Info	1xNVIDIA Q4000M					
	Disks/Optical/Floppy		ATA 10K SI		VD+-RW Su	iperMulti SA	TA
	Power Supply	400W 90% Custom PSU					
	Other						
Energy Consumption			VAC		VAC		VAC
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	133	3 W	130) W	135	5 W
	Windows Busy Typ (S0)	288	3 W	275	5 W	290) W
	Windows Busy Max (S0)) 304 W 296 W		306 W			
	Sleep (S3)	3.19 W	3.08 W	3.38 W	3.27 W	3.18 W	3.07 W
	Off (S5)	1.01 W	0.90 W	1.19 W	1.07 W	1.00 W	0.88 W
	Zero Power Mode (EuP)						
Heat Dissipation**		115	VAC	230	VAC	100	VAC
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	4	54	44	14	46	61
	Windows Busy Typ (S0)	98	33	938		990	
	Windows Busy Max (S0)	10	37	10	09	10	44
	Sleep (S3)	10.9	10.5	11.5	11.2	10.9	10.5
	Off (S5)	3.45	3.07	4.06	3.65	3.41	3.00
	Zero Power Mode (EuP)						
			S.				

(Entry level)	Processor Info	Intel i3-2120 2-core 3.3 GHz			
	Memory Info	2 x 2 GB DDR3 1333 MT/s			
	Graphics Info	Internal Graphics			
	Disks/Optical/Floppy	2 x 300 GB Solid State Drives (SSD) / DVD R/RW dual layer LightScribe			

Declared Noise Emissions (in		Sound Power (LWAd, bels)	Desktop Sound Pressure (LpAm, decibels)
\rightarrow	Idle	2.8 Bels	20 dB
	Hard drive Operating (random reads)	Same as Idle	Same as Idle
	DVD-ROM Operating (sequential reads)	4.9 Bels	37 dB
X			1

System Configuration	Processor Info	Intel®Core™3-3220 2-core 3.3 GHz
(Entry level)	Memory Info	2 x 2 GB DDR3 1600 MT/s
	Graphics Info	NVIDIA Q1000M MXM
	Disks/Optical/Floppy	1 x 500 GB 7200 RPM SATA / DVD R/RW dual layer LightScribe

Declared Noise Emissions (in		Sound Power (LWAd, bels)	Desktop Sound Pressure (LpAm, decibels)
accordance with ISO	Idle	3.2 Bels	23 dB
7779 and ISO 9296)	Hard drive Operating (random reads)	3.4 Bels	23 dB
	DVD-ROM Operating (sequential reads)	5.3 Bels	36 dB
с			<u>v</u>

System Configuration	Processor Info	Intel E3-1280v2 4-core 3.6 GHz
(High-end)	Memory Info	4 x 4 GB DDR3 1600 MT/s
	Graphics Info	NVIDIA Q4000M MXM
	Disks/Optical/Floppy	2 x 600 GB 10K RPM SATA / DVD R/RW dual layer LightScribe
1	i .	

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)		Sound Power (LWAd, bels)	Desktop Sound Pressure (LpAm, decibels)
	Idle	3.3 Bels	24 dB
	Hard drive Operating (random reads)	4.1 Bels	32 dB
	DVD-ROM Operating (sequential reads)	5.3 Bels	39 dB

Environmental Requirements	Temperature	Operating: 40° to 95° F (5° to 35° C) Non-operating: -40° to 140° F (-40° to 60° C)
	Humidity	Operating: 8% to 85% RH, non-condensing Non-operating: 8% to 90% RH, non-condensing
	Maximum Altitude	Operating: 10,000 feet (3,000 m) Non-operating: 30,000 feet (9,100 m)
	Dynamic (new)	Shock Operating: ½sine: 40g, 2-3ms (~62 cm/sec) Non-operating: ½sine: 160 cm/s, 2-3ms (~105g) square: 422 cm/s, 20g
		Vibration Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025 g ² /Hz Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g ² /Hz Values represent individual shock events and do not indicate repetitive
		shock events. Values do not indicate continuous vibration.
	Cooling	Above 5,000 ft (1524 m) altitude, maximum operating temperature is de-rated by 1.8° F (1° C) per 1,000 ft (305 m) elevation increase



System Technical Specifications		
Physical Securit	y and Serviceability	
Access Panel	Tool-less	
	Includes system board and memory information	
Expansion Cards	MXM graphics assembly is tool-less.	
	MiniPCIe cards are screw-in.	
Processor Socket	Tool-less, except for the processor heatsink.	
Green User Touch Points	Yes, on tool-free internal chassis mechanisms	
Color-coordinated	Yes	
Cables and Connectors		
Memory	Tool-less	
System Board	Screw-In for motherboard, Rear IO and Side IO boards.	
Dual Color Power and		
HD LED on Side of		
Computer		
Configuration Record SW	Yes	
Over-Temp Warning or Screen	Yes	
Restore CD/DVD Set	Restores the computer to its original factory shipping operating system. Orderable with the workstation, or available from Support.	
Dual Function Side	Causes a fail-safe power off when held for 4 seconds	
Power Switch		
Cable Lock Support	Yes, Kensington Cable Lock (optional): Locks side cover and secures chassis from theft 3mm x 7mm slot at rear of system	
Solenoid Lock and	No, Solenoid Lock	
Hood Sensor	Yes, Hood Sensor	
	The Sensor Kit detects when the access panel has been opened.	
Serial, Parallel, USB,	Yes, enables or disables USB, audio, and network ports	
Audio, Network, Enable/Disable Port		
Control		
Removable Media	Yes, prevents ability to boot from removable media on supported devices (and can disable writes	
Write/Boot Control	to media)	
Power-On Password	Yes, prevents an unauthorized person from booting up the workstation.	
Setup Password	Yes, prevents an unauthorized person from changing the workstation configuration	
3.3V Aux Power LED	No	
on System PCA	Nee -	
NIC LEDs (integrated) (Green & Amber)	Yes	
CPUs and Heatsinks	A T-15 Torx or flat blade screwdriver is needed to remove the CPU heatsink before the CPU can	
Dowor Currely	be removed. CPU removal is tool-less	
Power Supply Diagnostic LED	Yes	
Side Power Button	Yes, ACPI multi-function	



Side Power LED

Side Hard Drive

Activity LED

Yes, blue (normal), red (fault)

Yes, green

Side ODD Activity LED	Yes, green
Internal Stereo Speakers	Yes, Two 4W speakers
System/Emergency ROM Flash Recovery	Recovers corrupted system BIOS.
Cooling Solutions	Air cooled forced convection
Power Supply Fans	40 mm x 40 mm x 20 mm 4-wire PWM (non-serviceable)
CPU Heatsink Fan	Yes, Two 80 mm blowers
MXM Heatsink Fan	Yes, One 110 mm blower with MXM graphics assembly
System Blower	Yes, 110 mm blower
HP Advanced System Diagnostics Offline Edition	HP Vision Diagnostics utility must be booted from USB or CD, and enables you to perform testing and to view critical computer hardware and software configuration information from various sources.
Access Panel Key Lock	No
ACPI-Ready Hardware	Advanced Configuration and Power Management Interface (ACPI).
	 Allows the system to wake from a low power mode Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system
Trusted Platform Module Chip with optional ProtectTools Software	Yes
Integrated Chassis Handles	Yes, One on top-rear of system
Power Supply	Tool-less
miniPCle Card Retention	Yes
Flash ROM	Yes
Diagnostic Power Switch LED on board	No
Clear Password Jumper	Yes
Clear CMOS Button	Yes
CMOS Battery Holder	Yes
DIMM Connectors	Yes
HP ProtectTools Security Manager	Yes - Not supported on Linux

BIOS	
BIOS 32-bit Services	Standard BIOS 32-bit Service Directory Proposal v0.4
ΑΤΑΡΙ	ATAPI Removable Media Device BIOS Specification Version 1.0.
BBS	BIOS Boot Specification v1.01.
WMI Support	WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM) and WBEM specifications.
BIOS Boot Spec 1.01+	Provides more control over how and from what devices the workstation will boot.
BIOS Power On	Users can define a specific date and time for the system to power on.



ROM Based Computer Setup Utility (F10)	Review and customize system configuration settings controlled by the BIOS.	
System/Emergency ROM Flash Recovery with Video	Recovers system BIOS in corrupted Flash ROM.	
Replicated Setup	Saves BIOS settings to USB flash device in human readable file. Repset.exe utility can then replicate these settings on machines being deployed without entering Computer Configuration Utility (F10 Setup).	
SMBIOS	System Management BIOS 2.7.1, for system management information	
Boot Control	Disables the ability to boot from removable media on supported devices.	
Memory Change Alert	Alerts management console if memory is removed or changed.	
Thermal Alert	 Monitors the temperature state within the chassis. Three modes: NORMAL - normal temperature ranges. ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid shutdown or provide for a smoother system shutdown. SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the 	
	computer without warning before hardware component damage occurs.	
Remote ROM Flash	Provides secure, fail-safe ROM image management from a central network console.	
ACPI (Advanced Configuration and Power Management Interface)	Allows the system to enter and resume from low power modes (sleep states). Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.	
Ownership Tag	A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.	
Remote Wakeup/ Remote Shutdown	System administrators can power on, restart, and power off a client computer from a remote location.	
Instantly Available PC (Suspend to RAM - ACPI sleep state S3)	Allows for very low power consumption with quick resume time	
Remote System Installation via F12 (PXE 2.1) (Remote Boot from Server)	Allows a new or existing system to boot over the network and download software, including the operating system.	
ROM revision levels	Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS) so that management SW applications can use and report this information.	
System board revision level	Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified.	
Start-up Diagnostics (Power-on Self-Test)	Assesses system health at boot time with selectable levels of testing.	
Auto Setup when new hardware installed	System automatically detects addition of new hardware.	
Keyboard-less Operation	The system can be booted without a keyboard	
Localized ROM Setup	Common BIOS image supports System Configuration Utility (F10 Setup) menus in 12 languages with local keyboard mappings.	
Asset Tag	The user or MIS to set a unique tag string in non-volatile memory.	
Per-slot Control	Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually.	
Adaptive Cooling	Control parameters are set according to detected hardware configuration for optimal acoustics.	



System Technical Specifications

Pre-boot Diagnostics	(Pre-video) critical errors are reported via beeps and blinks on the power LED.
Intel®Active Management Technology (AMT)	AMT 7.0; Allows workstation status to be monitored on a remote console
Industry Standard Specification Support	
UEFI Specification Revision	2.3.1
ACPI	Advanced Configuration and Power Management Interface, Version 1.0
ASF	No
ATA (IDE)	AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b
CD Boot	"El Torito" Bootable CD-ROM Format Specification Version 1.0
EDD	 Enhanced Disk Drive Specification Version 1.1 BIOS Enhanced Disk Drive Specification Version 3.0
EHCI	Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0
PCI Express	 PCI Express Mini Card Electromechanical Specification Revision 1.2 PCI Express Base Specification, Revision 2.0 MXM Graphics Module Mobile PCI Express Module Electromechanical Specification Version 3.0, Revision 1.1
РММ	POST Memory Manager Specification, Version 1.01
SATA	 Serial ATA Specification, Revision 1.0a Serial ATA II: Extensions to Serial ATA 1.0, Revision 2.6 Serial ATA II Cables and Connectors Volume 2 Gold Serial ATA III: Revision 3.0 Specification
SPD	PC SDRAM Serial Presence Detect (SPD) Specification, Revision 1.2B
ТРМ	Trusted Computing Group TPM Specification Version 1.2
USB	 Universal Serial Bus Revision 1.1 Specification Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.0 Specification

Social and Environmental Responsibility

 Eco-Label Certifications
 This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

 • ENERGY STAR®(energy-saving features available on selected configurations-Windows only)

- US Federal Energy Management Program (FEMP)
- China Energy Conservation Program
- IT ECO declaration

Batteries	The battery in this product complies with EU Directive 2006/66/EC Battery size: CR2032 (coin cell) Battery type: Lithium Metal
	The battery in this product does not contain:

- Mercury greater than 5ppm by weight
- Cadmium greater than 10ppm by weight
- Lead greater than 40ppm by weight



Restricted Material Usage	This product meets the material restrictions specified in HP's General Specification for the Environment. http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf Hewlett-Packard is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis.
Low Halogen Statemer	It his product is low halogen except for power cords, cables and peripherals, as well as the following customer-configurable internal components: 3 ½ SAS HDDs, LSI 9260-8i SAS 6Gb/s ROC RAID Card, Creative Recon3D PCIe Audio Card, Liquid Cooling Solution and Broadcom 5761 Gigabit PCIe NIC are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.
End-of-Life Management and Recycling	Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. This product is greater than 90% recyclable by weight when properly disposed of at end of life.
Hewlett-Packard Corporate Environmental	For more information about HP's commitment to the environment: Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
Information	Eco-label certifications http://www.hp.com/hpinfo/globalcitizenship/environment/productdesign/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/operations/envmanagement.html
Additional Information	 This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. Plastic parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043. This product is >90% recycle-able when properly disposed of at end of life. EPEAT Gold - ENERGY STAR qualified configurations of this product are in compliance with the IEEE 1680 (EPEAT) standard at the Gold level where HP registers workstation products. See http://ww2.epeat.net/CompanyDetail.aspx?CompanyID=24 for registration status in your country.
Packaging	 HP Workstation product packaging meets the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/society/gen_specifications.html Does not contain restricted substances listed in HP Standard 011-1 General Specification for the Environment Does not contain ozone-depleting substances (ODS) Does not contain heavy metals (lead, mercury, cadmium or hexavalent chromium) in excess of 100 ppm sum total for all heavy metals listed Maximizes the use of post-consumer recycled content materials in packaging materials All packaging material is recyclable All packaging material is designed for ease of disassembly Reduced size and weight of packages to improve transportation fuel efficiency Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards formattin
Packaging Materials	
Internal	Cushions and plastic bags made of low density polyethylene (LDPE).
External	Outer carton, accessories carton, and insert made of corrugated paper board.

Manageability	
Industry Standard Specifications	This product meets the following industry standard specifications for manageability functionality:
	DASH 1.1 required functionalities via integrated Intel LAN



Intel Active	Intel Active Management Technology (AMT) 7.0
Management Technology (AMT)	An advanced set of remote management features and functionality which provides network administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 7.0 includes the following advanced management functions:
	 Power Management (on, off, reset) Hardware Inventory (includes BIOS and firmware revisions Hardware Alerting
	 Agent Presence System Defense Filters SOL/IDER
	 Cisco NAC/SDN Support ME Wake-on-LAN DASH 1.1 compliance
	 IPv6 Support Fast Call for Help - a client inside or outside the firewall may initiate a call for help via BIOS screen, periodic connections, or alert triggered connection o Remote Scheduled Maintenance - pre-schedule when the PC connects to the IT or service
	 Provider console for maintenance - pre-schedule when the PC connects to the PT of service provider console for maintenance. Remote PCs can get required patches, be inventoried, etc by connecting to their IT console or Service Provider when it's convenient Remote Alerts - automatically alert IT or service provider if issues arise Access Monitor - Provides oversight into Intel®AMT actions to support security requirement
	 PC Alarm Clock Microsoft NAP Support Host Base set-up and configuration
	Management Engine (ME) firmware roll back Enhanced KVM resolution
Intel®vPro™ Technology	The HP Z1 Workstation supports Intel vPro technology when configured with a processor branded "featuring Intel vPro Technology"
Remote Manageability Software Solutions	 LANDesk Management Suite (PSG recommended solution) Microsoft System Center Configuration Manager HP Client Automation Enterprise
System Software Manager	For questions or support for manageability needs, please visit http://www.hp.com/go/easydeploy For questions or support for SSM, please visit: http://www.hp.com/go/ssm
Service, Support, and Warranty	On-site Warranty and Service (Note 1): One, Three, Four & Five -years (options available), limited warranty and service offering delivers on-site, next business-day (Note 2) service for parts and labor and includes free telephone support (Note 3) 8am - 5pm. Global coverage (Note 2) ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering.
	NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply. NOTE 2 : On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country. NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.
	HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at http://www.hp.com/go/lookuptool. Additional HP Care Pack Services information by product is available at http://www.hp.com/hps/carepack. Service levels



System Technical Specifications

	and response times for HP Care Packs may vary depending on your geographic location.
Product Change	Program to proactively communicate Product Change Notifications (PCNs) and Customer
Notification	Advisories by email to customers, based on a user-defined profile.
	PCNs provide advance notification of hardware and software changes to be implemented in
	the factory providing time to plan for transition.
	Customer Advisories provide concise, effective problem resolution, greatly reducing the
	need to call technical support.

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Stable & Consistent Offerings

Hard Drives	Product #	Offering		
	A2H01AV	HP 250GB SATA 7200 1st HDD		
	A2H02AV	HP 500GB SATA 7200 1st HDD		
	A3S86AV	HP 300GB SATA 10K SFF 1st HDD		
	A3S88AV	HP 300GB SATA 10K SFF 2nd HDD		
Memory	Product #	Offering		
	A2H27AV	HP 4GB (2x2GB) DDR3-1600 nECC RAM		
	A2H29AV	HP 4GB (2x2GB) DDR3-1600 ECC RAM		
	A2H30AV	HP 8GB (4x2GB) DDR3-1600 ECC RAM		
	A2H32AV	HP 16GB (4x4GB) DDR3-1600 ECC RAM		
Optical and Removal	bleProduct #	Offering		
Storage	A2H18AV	HP 8X DVD RW SuperMulti Slot Load Drive		
Input Devices	Product #	Offering		
	A2H09AV	HP USB Standard Keyboard		
	A2H10AV	HP USB Optical Scroll Mouse		
	A6T05AV	HP Wireless Keyboard and Mouse		
Operating Systems	Product #	Offering		
- p	A2H12AV	MS Windows 7 Professional 32-Bit OS		
	A2H13AV	MS Windows 7 Professional 64-bit OS		
		Nº V		
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	\times 07			
\prec_{k}	el. 05/20			



Technical Specifications - Processors

Processors Intel®Xeon®processor E3-1280v2, Quad-Core, 8 MB cache, 3.6 GHz, up to 4.0 GHz with Intel Turbo Boost Technology Intel®Xeon®processor E3-1245v2, Quad-Core, 8 MB cache, 3.4 GHz, up to 3.8 GHz with Intel Turbo Boost Technology Intel®Xeon®processor E3-1225v2, Quad-Core, 8 MB cache, 3.2 GHz, up to 3.6 GHz with Intel Turbo Boost Technology Intel®Xeon®processor E3-1225v2, Quad-Core, 8 MB cache, 3.2 GHz, up to 3.6 GHz with Intel Turbo Boost Technology Intel®Core™5-3470 processor, Quad-Core, 6 MB cache, 3.2 GHz, up to 3.6 GHz with Intel Turbo Boost Technology Intel®Core™5-3470 processor, Quad-Core, 3 MB cache, 3.2 GHz, up to 3.6 GHz with Intel Turbo Boost Technology Intel®Core™5-3470 processor, Quad-Core, 3 MB cache, 3.3 GHz

MMM 2000into



1051-891-2000 Tel: 051-891 Technical Specifications - Hard Drives

SATA (Serial ATA) Hard 500GB SATA 10K rpm		Capacity	500GB	
• •	SFF HDD	Height	0.6 in; 1.53 cm	
Workstations		Width	Media Diameter	2.5 in; 6.36 cm
			Physical Size	2.75 in; 6.99 cm
		Interface	Serial ATA (6Gb/s)	
		Synchronous Transfer Rate (Maximum)	Up to 600MB/s	
		Buffer	64MB	
		Cache	Adaptive	
		Seek Time (typical	Single Track	1.2ms (typical)
		reads, includes controller	Average	3.6ms
		overhead, including settling)	Full Stroke	9.0ms (typical)
		Rotational Speed	10K rpm	
		Operating Temperature		
		J		
	1TB SATA 10K rpm	Capacity	1TB	
	SFF HDD	Height	0.6 in; 1.53 cm	
		Width	Media Diameter	2.5 in; 6.36 cm
			Physical Size	2.75 in; 6.99 cm
	Interface	Serial ATA (6Gb/s)		
	Synchronous Transfer Rate (Maximum)	Up to 600 MB/s		
		Buffer	64MB	
		Cache	Adaptive	
		Seek Time (typical	Single Track	1.2ms (typical)
		reads, includes controller overhead, including settling)	Average	3.6ms
			Full Stroke	9.0ms (typical)
		Rotational Speed	10K rpm	
		Operating Temperature		
	6			
	250GB SATA 7200 rpm	Capacity	250 GB	
	6Gb/s 3.5" HDD	Height	1 in; 2.54 cm	
X	. 9/	Width	Media Diameter	3.5 in; 8.9 cm
			Physical Size	4 in; 10.17 cm
\sim		Interface	Serial ATA (6.0Gb/s), N	NCQ enabled
		Synchronous Transfer Rate (Maximum)	Up to 600MB/s	
		Buffer	8 MB	
		Seek Time (typical	Single Track	2 ms
		reads, includes controller	Average	11 ms
		overhead, including settling)	Full Stroke	21 ms
		Rotational Speed	7,200 rpm	
		Logical Blocks	488,397,168	
		Operating Temperature		
			, , ,	

Technical Specificati	ons - Hard Drives			
	500GB SATA 7200 rpm 6Gb/s 3.5" HDD	Capacity	500GB	
		Height	1 in; 2.54 cm	
		Width	Media Diameter	3.5 in; 8.9 cm
			Physical Size	4 in; 10.17 cm
		Interface	Serial ATA (6.0Gb/s), N	NCQ enabled
		Synchronous Transfer Rate (Maximum)	Up to 600MB/s	
		Buffer	16MB	
		Seek Time (typical	Single Track	2 ms
		reads, includes controller	Average	11 ms
		overhead, including settling)	Full Stroke	21 ms
		Rotational Speed	7,200 rpm	
		Logical Blocks	976,773,168	
		Operating Temperature		
		J		
	1TB SATA 7200 rpm	Capacity	1 Terabyte (1000 GB)	
	6Gb/s 3.5" HDD	Height	1 in; 2.54 cm	
		Width	Media Diameter	3.5 in; 8.9 cm
			Physical Size	4.0 in; 10.17 cm
		Interface	Serial ATA (6.0Gb/s), N	NCQ enabled
		Synchronous Transfer Rate (Maximum)	Up to 600MB/s	
		Buffer	32MB	
		Seek Time (typical	Single Track	2 ms
		reads, includes controller	Average	11 ms
		overhead, including settling)	Full Stroke	21 ms
		Rotational Speed	7,200 rpm	
		Logical Blocks	1,953,525,168	
	0	Operating Temperature		
	3.0TB SATA 7200 rpm	Capacity	3.0TB	
	6Gb/s 3.5" HDD	Height	1 in; 2.54 cm	
		Width	Media Diameter	3.5 in; 8.9 cm
X	• /		Physical Size	4.0 in; 10.17 cm
×.		Interface	Serial ATA (6.0Gb/s), N	NCQ enabled
		Synchronous Transfer Rate (Maximum)	Up to 6.0 Gb/s	
		Buffer	64MB	
		Seek Time (typical	Single Track	0.6 ms
	reads, includes controller overhead, including	Average	11 ms	
	settling)	Full Stroke	Not specified	
		Rotational Speed	7200 rpm	
		Operating Temperature	41° to 140° F (5° to 60° C)	
		-		
300GB SATA 10K rpm	Capacity	300,069,052,416 bytes		
	SFF HDD	Height	0.6 in; 1.53 cm	

HP Z1 Workstation

Technical Specifications - Hard Drives

		Width	Media Diameter	2.5 in; 6.36 cm
			Physical Size	2.75 in; 6.99 cm
		Interface	Serial ATA (3.0 Gb/s), Queuing enabled	Native Command
		Synchronous Transfer Rate (Maximum)	Up to 300 MB/s	
		Buffer	16 MB	
		Seek Time (typical	Single Track	0.7 ms (maximum)
		reads, includes controller	Average	4.4 ms
		overhead, including settling)	Full Stroke	9.5 ms
		Rotational Speed	10,000 rpm	E I
		Logical Blocks	586,072,368	/
		Operating Temperature		
		operating remperature		
	600GB SATA 10K rpm	Capacity	600GB	
	SFF HDD	Height	0.6 in; 1.53 cm	
		Width	Media Diameter	2.5 in; 6.36 cm
			Physical Size	2.75 in; 6.99 cm
		Interface	Serial ATA (3.0Gb/s)	·
		Synchronous Transfer Rate (Maximum)	Up to 300MB/s	
		Buffer	32MB	
		Cache	Segmentable	
		Seek Time (typical	Single Track	0.4 ms (max)
		reads, includes controller	Average	3.6 ms
		overhead, including settling)	Full Stroke	9.0 ms
		Rotational Speed	10,000 rpm	
		Logical Blocks	1,172,123,568	
		Operating Temperature)
HP Solid State Drives	HP 256GB SATA 6Gb/s	Capacity	256GB	
for Workstations	SSD	Height	0.28 in; 0.7 cm	
	/ 0 /	Interface	SATA 6Gb/s	
		Synchronous Transfer Rate (Maximum)	Up to 500MB/s (Seque	ential Read)
		Operating Temperature	e32° to 158° F (0° to 70° C))
	HP 512GB SATA 6Gb/s	Capacity	512GB	
	SSD	Height	0.28 in; 0.7 cm	
		Width	Physical Size	2.5 in; 6.36 cm
		Interface	SATA 6Gb/s	- ,
		Synchronous Transfer Rate (Maximum)		ential Read)
		Operating Temperature	e32° to 158° F (0° to 70° C)	

Technical Specifications - Graphics

Integrated Intel HD Graphics Media	Form Factor Graphics Controller	Integrated Intel Integrated Graphics Media Accelerator HD
Accelerators	Memory	Unified Memory Architecture (UMA) frame buffer. Graphics memory is shared with system memory. Size selectable between 64 MB to 512 MB via BIOS setting. Default size is 64 MB. Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (Intel DVMT 5.0), to provide an optimal balance between graphics and system memory use.
	Connectors	1 Embedded DisplayPort to LCD panel, 1 DisplayPort on rear IO Graphics adapters are orderable as an accessory as necessary.
	Maximum Resolution	Display Port: 2560 x 1600
	RAMDAC	Integrated, 350 MHz
	Display Output	Integrated dual independent monitor support facilitated via one embedded DP and one DisplayPort integrated on the rear IO. VGA support via optional DisplyPort to VGA adapter.
	Supported Graphics APIs	Intel HD Graphics 2000: Microsoft DirectX 10, OpenGL 2.1 Intel HD Graphics P3000: Microsoft DirectX 10.1, OpenGL 3.0
NVIDIA Quadro 500M	Form Factor	MXM v3.0 Type A (82mm x 70mm)
1GB Graphics	Graphics Controller	N12M-Q3, 560MHz core clock
	Bus Type	PCI Express x16 (part of MXM v3.0 connector)
	Memory	1GB DDR3, 128 bit wide interface, 800MHz
	Connectors	One MXM v3.0 connector (285-pin)
	Maximum Resolution	2 x 2560x1600 @ 60Hz digital displays In Z1 application: - Internal Display: 2560x1440 - External Display via DP connector: 2560x1600
	RAMDAC	Not Applicable
	Image Quality Feature	 S Capable of 10-bit per channel (3 channels) internal display processing, including hardware support for 10-bit per channel scan-out 64-bit texture filtering and blending Advanced vertex and pixel shaders, antialiasing, 16x anisotropic filtering MPEG-2 HD and WMV HD video playback (1920x1080p) H.264 hardware decode acceleration AES-128 CTR/CBC/ECB decryption modes supported Advanced video algorithms NVIDIA Digital Vibrance Control 3.0
4	Shading Architecture	Shader Model 5.0 support 96 processor cores
	Supported Graphics APIs	Full IEEE 764-2008 32-bit or 64-bit precision DirectX 11.0 Shader Model 5.0 OpenGL 4.0 Compute API support for NVIDIA CUDA C, CUDA C++, DirectCompute 5.0, OpenCL, Java, Python and Fortran
	Available Graphics Drivers	Windows 7 32-bit and 64-bit SUSE Linux Enterprise Desktop 11 HP Linux Installer Kit
	Power Consumption	See www.hp.com/go/support for HP supported NVIDIA graphics drivers <35W

Technical Specifications - Graphics

NVIDA Quadro 1000M	Form Factor	MXM v3.0 Type A (82mm x 70mm)
2GB Graphics	Graphics Controller	N12P-Q1, 700MHz core clock
	Bus Type	PCI Express x16 (part of MXM v3.0 connector)
	Memory	2GB DDR3, 128-bit wide interface, 900MHz
	Connectors	One MXM v3.0 connector (285-pin)
	Maximum Resolution	2 x 2560x1600 @ 60Hz digital displays In Z1 application: - Internal Display: 2560x1440 - External Display via DP connector: 2560x1600
	RAMDAC	Not Applicable
	Image Quality Feature	 S Capable of 10-bit per channel (3 channels) internal display processing, including hardware support for 10-bit per channel scan-out 64-bit texture filtering and blending Advanced vertex and pixel shaders, antialiasing, 16x anisotropic filtering MPEG-2 HD and WMV HD video playback (1920x1080p) H.264 hardware decode acceleration AES-128 CTR/CBC/ECB decryption modes supported Advanced video algorithms NVIDIA Digital Vibrance Control 3.0
	Shading Architecture	Shader Model 5.0 support 96 processor cores
	Supported Graphics APIs	Full IEEE 764-2008 32-bit or 64-bit precision DirectX 11.0 Shader Model 5.0 OpenGL 4.0 Compute API support for NVIDIA CUDA C, CUDA C++, DirectCompute 5.0, OpenCL, Java, Python and Fortran
	Available Graphics Drivers	Windows 7 32-bit and 64-bit SUSE Linux Enterprise Desktop 11 HP Linux Installer Kit
	Power Consumption	See www.hp.com/go/support for HP supported NVIDIA graphics drivers 42W
NVIDIA Quadro	Form Factor	MXM v3.0 Type B (82mm x 105mm)
K3000M 2GB Graphics	Graphics Controller	N14E-Q1, 650MHz core clock
	Bus Type	PCI Express x16 (part of MXM v3.0 connector)
	Memory	2GB GDDR5, 256-bit wide interface, 89GB/s
	Connectors	One MXM v3.0 connector (285-pin)
× ~ ~	Maximum Resolution	In Z1 application: - Internal Display: 2560x1440 - External Display via DP connector: 2560x1600
	RAMDAC	Not Applicable
	Image Quality Feature	 SCapable of 10-bit per channel (3 channels) internal display processing, including hardware support for 10-bit per channel scan-out 64-bit texture filtering and blending Advanced vertex and pixel shaders, antialiasing, 16x anisotropic filtering MPEG-2 HD, MPEG-4 HD, DVIX, and WMV HD video playback (1920x1080p) H.264 hardware decode acceleration AES-128 CTR/CBC/ECB decryption modes supported Advanced video algorithms

Technical Specifications - Graphics

		NVIDIA Digital Vibrance Control 3.0
	Shading Architecture	Shader Model 5.0 support 576 processor cores
	Supported Graphics APIs	Full IEEE 764-2008 32-bit or 64-bit precision DirectX 11, Shader Model 5.0, OpenGL 4.1 Compute API support for NVIDIA CUDA C, CUDA C++, DirectCompute 5.0, Java, Python and Fortran
	Available Graphics Drivers	Windows 8 32-bit and 64-bit Windows 7 32-bit and 64-bit SUSE Linux Enterprise Desktop 11 HP Linux Installer Kit
		See www.hp.com/go/support for HP supported NVIDIA graphics drivers
	Power Consumption	75W
NVIDIA Quadro K4000M 4GB	Form Factor	MXM v3.0 Type B (82mm x 105mm)
Graphics	Graphics Controller	N14E-Q3, 600MHz core clock
	Bus Type	MXM v3.0
	Memory	4GB GDDR5, 256-bit wide interface, 89GB/s
	Connectors	One MXM v3.0 connector (285-pin)
	Maximum Resolution	In Z1 application: - Internal Display: 2560x1440 - External Display via DP connector: 2560x1600
	RAMDAC	Not Applicable
	Image Quality Feature	 S Capable of 10-bit per channel (3 channels) internal display processing, including hardware support for 10-bit per channel scan-out 64-bit texture filtering and blending Advanced vertex and pixel shaders, antialiasing, 16x anisotropic filtering MPEG-2 HD, MPEG-4 HD, DVIX, and WMV HD video playback (1920x1080p) H.264 hardware decode acceleration AES-128 CTR/CBC/ECB decryption modes supported Advanced video algorithms NVIDIA Digital Vibrance Control 3.0
	Shading Architecture	Shader Model 5.0 support 960 processor cores
	Supported Graphics APIs	Full IEEE 764-2008 32-bit or 64-bit precision DirectX 11.0, Shader Model 5.0, OpenGL 4.1 Compute API support for NVIDIA CUDA C, CUDA C++, DirectCompute 5.0, Java, Python and Fortran
	Available Graphics Drivers	Windows 8 32-bit and 64-bit Windows 7 32-bit and 64-bit SUSE Linux Enterprise Desktop 11 HP Linux Installer Kit
	Power Consumption	See www.hp.com/go/support for HP supported NVIDIA graphics drivers 100W

Technical Specifications - Optical and Removable Storage

HP Slot Load DVD+/-	Description	Slim-Line, Slot-load				
RW Drive	Mounting Orientation					
	Interface Type	SATA				
	••	Dimensions (WxHxD) 12.7 x 1.2 x 12.9 cm (5 x 0.5 x 5 in) Supported Media TypesDVD-RAM DVD+R DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW				
	, ,					
		CD-R CD-RW				
	Disc Capacity	DVD-ROM 5/9/10/18 G DVD-8 (Read Only) 4.7G DVD±R/RW (I DVD±R Dual (Read 80mm DVD		Write)		
			DVD-RAM (Read & \	/ .		
		CD-ROM	700/650MB CD-Rew	cordable (Read & Write) ritable (Read & Write) eed CD-Rewritable (Read Jltra+ Speed CD-		
	Access Times	Full Stroke DVD	< 270 ms (seek)			
		Full Stroke CD	< 250 ms (seek)			
	Maximum Data Transfer Rates	CD ROM Read	CD-ROM, CD-R and Up to 24X	CD-RW		
		DVD ROM Read	DVD-RAM	Up to 5X		
			DVD Single layer	Up to 8X		
			DVD Dual Layer	Up to 6X		
	Power	Source	SATA DC power receptacle			
		DC Power Requirements	5 VDC ± 5%-100 mV	ripple p-p		
		DC Current	5 VDC 40 mA typica	I, 800 mA maximum		
	Operating	Temperature	41° to 122° F (5° to 50° C)			
	Environmental (all conditions non-	Relative Humidity	10% to 90%			
	condensing)	Operating Systems Supported	Business 32*, Windo 32*, Windows XP Pro XP Home 32*. Red Hat Enterprise L Desktop/Workstatior	ness 64*, Windows Vista ows Vista Home Basic ofessional or Windows .inux(RHEL) WS4, 5, 6 n, ise Desktop 10 & 11,		
			•	for this device. Native by the operating system.		
		Kit Contents	Factory integrated or	nly. Not available as a kit.		
HP Blu-ray Writer Slot Load	Interface Type	Slim-line, Slot-load SATA				
	Dimensions (WxHxD) Disc Formats	12.7 x 1.2 x 12.9 cm (5 BD-ROM BD-R	x u.5 x 5 in)			



Technical Specifications - Optical and Removable Storage

		5		
		BD-RE DVD-RAM DVD+R DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW		
	Disc Capacity	DVD-ROM	8.5 GB DL or 4.7 GB s	
	. <u> </u>	Blu-ray	50 GB DL or 25 GB sta	andard
	Access Times	Full Stroke DVD	< 250 ms (seek)	
		Full Stroke CD	< 210 ms (seek)	
		Blu-ray	Blu-ray	050 / 000
		Startup Time (Time to drive ready from tray	BD-ROM (SL/DL)	25S / 28S
		loading)	BD-R (SL/DL)	25S / 28S
		0,	BD-RE (SL/DL)	25S / 28S
			DVD-ROM (SL/DL)	18S / 18S
			DVD-R (SL/DL)	25S / 25S
			DVD-RW	25S
			DVD+R (SL/DL)	25S / 25S
			DVD+RW	25S
			DVD-RAM	45S 45S
	Maximum Data	CD ROM Read	CD-ROM	
	Transfer Rates	CD ROW Read	CD-ROM CD-R	Up to 40X Up to 40X
			CD-RW	Up to 40X
		DVD ROM Read	DVD-RAM	Up to 5X
	(DVD+RW	Up to 10X
			DVD-RW	Up to 10X
			DVD+R DL	Up to 8X
	6		DVD-R DL	Up to 8X
			DVD-ROM	Up to 16X
	67		DVD-ROM DL	Up to 8X
			DVD+R	Up to 12X
			DVD-R	Up to 12X
10		Blu-Ray	BD-ROM	Up to 6X
\sim			BD-ROM DL	Up to 4.8X
			BD-R	Up to 6X
			BD-R DL	Up to 4.8X
			BD-R	Up to 6X
			BD-RE SL/DL	Up to 4.8X
	Power	Source	SATA DC power recept	otacle
		DC Power Requirements	5 VDC ± 5%-100 mV ripple p-p 12 VDC ± 10%-100 mV ripple p-p	
		DC Current	5 VDC -900 mA typica 12 VDC -1000 mA typi	ll, 1200 mA maximum ical, 1600 mA maximum
	Operating	Temperature	5° to 50° C (41° to 122° F)	



Technical Specifications - Optical and Removable Storage

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Environmental (all		
Environmental (all	Relative Humidity	15% to 80%
conditions non- condensing)	Maximum Wet Bulb Temperature	30° C (86° F)
	Operating Systems Supported Kit Contents	Windows 7 Professional 32-bit and 64-bit, Windows Vista Business 64*, Windows Vista Business 32*, Windows Vista Home Basic 32*, Windows 2000, Windows XP Professional or Windows XP Home 32*. Red Hat Enterprise Linux(RHEL) WS4, 5, 6 Desktop/Workstation, SUSE Linux Enterprise Desktop 10 & 11 * No driver is required for this device. Native support is provided by the operating system. HP Blue Laser RW Drive, Roxio Easy Media Creator software, Intervideo WinDVD Software, installation guide.
Disclaimer	digital connection, com and do not constitute d systems is not guarante may require a DVI or H	mat containing new technologies, certain disc, patibility and/or performance issues may arise, efects in the product. Flawless playback on all eed. In order for some Blu-Ray titles to play, they DMI digital connection and your display may HD-DVD movies cannot be played on this



Technical Specifications - Networking and Communications

Integrated Intel 82579LM PCIe GbE Controller	Connector	RJ-45
	Controller	Intel 82579LM GbE platform LAN connect networking controller
	Memory	24 KB FIFO packet buffer memory
	Data Rates Supported	10/100/1000 Mbps
	Compliance	802.1P, 802.1Q, 802.2, 802.3, 802.3ab, 802.3az, 802.3u
	Bus Architecture	PCI Express and SMBus
	Data Transfer Mode	PCIe-based interface for active state operation (S0 state) and SMBus for host and management traffic (Sx low power state)
	Hardware Certifications	FCC class B, Canada and US NRTL Mark, C-Tick for Australia, BSMI for Taiwan, VCCI for Japan, MIC for Korea, GOST for Russia, UL listed (E212044), European Union Notice (CE 0682)
	Power Requirement	Requires 3.3V and 1.05V or just 3.3V with integrated regulators
	Boot ROM Support	Yes
	Network Transfer Mode	Full-duplex; Half-duplex (not supported for the 1000BASE-T transceiver)
	Network Transfer Rate	10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps
	Management Capabilities	WOL, auto MDI crossover, PXE, Muti-port teaming, RSS, Advanced cable diagnostic. AMT 7.0 support

Summary of Changes

Date	Version History	Action	Description of Change
April 1, 2015	From v21 to v22	-	Memory terminology and notes. Entry and high level configurations from System Technical Specifications.

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